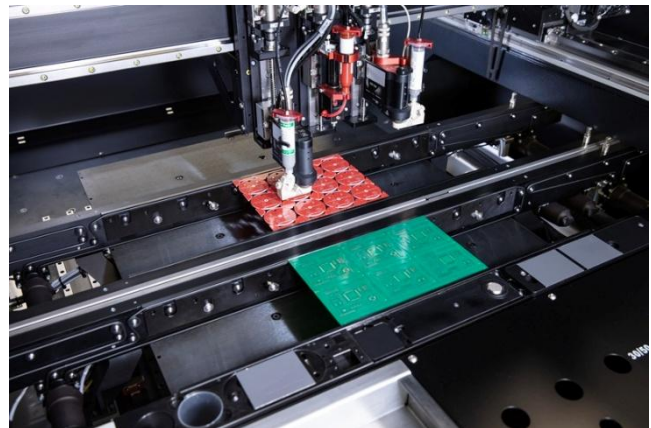


Essemtec to Highlight Advanced Dispensing Solutions for Complex Electronics at SMTA Space Coast

Aesch, Switzerland — October 2026 — Essemtec, a global leader in adaptive, highly flexible surface mount technology (SMT) solutions, is proud to announce that it will showcase its advanced dispensing technologies & Flexible All-in-One solutions for complex electronics assembly at the SMTA Space Coast Expo & Tech Forum, taking place November 12 at the Melbourne Auditorium in Melbourne, Florida. The company will highlight solutions for underfill, edge bonding, glue jetting, high speed solder paste Jetting, two-component (2K) materials and other precision dispensing applications that support demanding electronics manufacturing and advanced packaging requirements.

As electronics assemblies become increasingly complex and package geometries continue to evolve, manufacturers require dispensing processes that can deliver precise material placement, repeatable volumes and reliable coverage across a broad range of applications. Essemtec's flexible dispensing technology is designed to address these requirements with solutions spanning low- to high-viscosity materials and processes including underfill, dam and fill, encapsulation, adhesive dispensing, and 3D dispensing.

For advanced packaging and high-reliability assembly, Essemtec offers dispensing technologies for chip underfill and other material applications intended to improve mechanical robustness and protect sensitive components, key requirement for Aerospace Industries. The company's dispensing platforms such as the Spider and the Tarantula can support different valve technologies and process configurations, allowing manufacturers to select the appropriate approach for specific materials and assembly requirements.



Essemtec's dispensing portfolio includes piezo jet, shockwave jet, volume, screw and time-pressure valve technologies but also the new Dual Volume Valve for meter-mix application. The 2K dispensing capability supports two-component materials in ratios ranging from 1:1 to 10:1, while glue jetting enables high-speed, non-contact dispensing of adhesive materials in precisely controlled dots and geometries patterns. Laser-based height mapping can also compensate for substrate warpage and enable 3D dispensing applications.

The Essemtec' technologies are suited to a range of challenging applications, including underfill, edge bonding, dam and fill, cavity fill, encapsulation, silver epoxy and adhesive jetting. Essemtec also supports advanced packaging applications such as chip-on-chip, SiP and PoP assemblies, providing manufacturers with a flexible platform for increasingly sophisticated electronic devices using the All-in-One platforms Fox ultra and Puma ultra.

"Complex assemblies require dispensing processes that can adapt to the materials, geometries and reliability requirements of the application," said Frank Hart, Director, Essemtec USA. "Our goal at SMTA Space Coast is to show manufacturers how precise dispensing, jetting and multi-material



capabilities can help address challenging assembly requirements while improving process flexibility and repeatability.”

Essemtec’s dispensing technology can be configured on the Tarantula with up to three dispensing valves in a single machine, allowing different dispensing technologies to be combined without requiring equipment changeovers. Process-control capabilities can monitor dispensing characteristics and support adjustments for consistent results.

For more information about Essemtec and its full line of adaptive SMT solutions, visit www.essemtec.com.

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About Essemtec

Essemtec is renowned for its adaptive, highly flexible SMT pick-and-place equipment, sophisticated dispensers suitable for both high-speed and micro-dispensing, and intelligent production material storage and logistic systems. All products are equipped with advanced software packages, ensuring efficient material management and user-friendly operation. Essemtec’s solutions are implemented worldwide across various industries, reflecting the company’s commitment to quality and innovation.